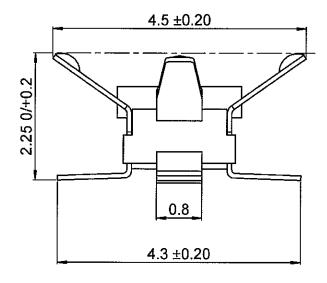
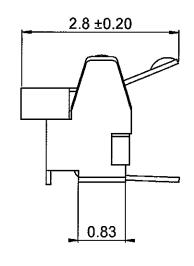
**REEL OF 100** 

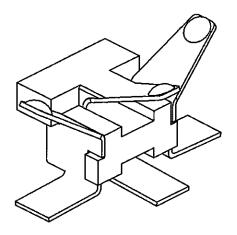
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Series: IMP









All dimensions are in mm.

		$\rightarrow$
COMPONENTS	MATERIALS	PLATINGS (μm)
ODY	BERYLLIUM COPPER	GOLD 0.5 OVER NICKEL 2
ENTER CONTACT OUTER CONTACT	BERYLLIUM COPPER BERYLLIUM COPPER	GOLD 0.5 OVER NICKEL 2 GOLD 0.5 OVER NICKEL 2
NSULATOR GASKET	POLYETHER ETHERCETONE 30% GF	
THERS PARTS		
	•	

Issue: 0444 C



**REEL OF 100** 

R107.064.070

Series: IMP

#### **PACKAGING**

Standard	Unit	Other
100	'W' option	Contact us

#### **SPECIFICATION**

#### **ELECTRICAL CHARACTERISTICS**

 $\begin{array}{ccc} \text{Impedance} & & \textbf{50} \;\; \Omega \\ \text{Frequency} & & \textbf{0-6} \;\; \text{GHz} \end{array}$ 

VSWR 1.5 + 0.000 x F(GHz) Maxi

Insertion loss RF leakage -

-( ]

Voltage rating
Dielectric withstanding voltage
Insulation resistance

 $\Omega$  Operating te

 $0.3 \quad \sqrt{F(GHz)} \text{ Maxi}$ 

NA - F(GHz)) dB Maxi 100 Veff Maxi

350 Veff mini 3000 MΩ mini

#### **ENVIRONMENTAL**

Operating temperature -40/+90 ° C

Hermetic seal

NA Atm.cm3/s

Panel leakage NA

#### **OTHERS CHARACTERISTICS**

Assembly instruction

Others:

#### **MECHANICAL CHARACTERISTICS**

Center contact retention

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 10 Cycles mini

Weight **0.013** g

Issue: 0444 C



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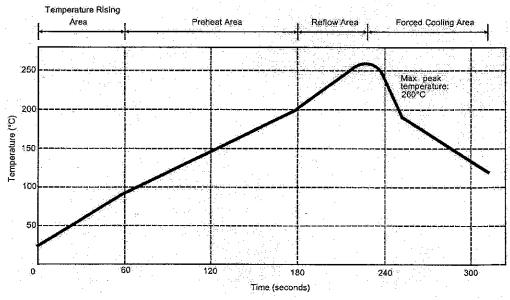
REEL OF 100

Series: IMP

#### SOLDER PROCEDURE

- 1. Deposition of solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
  - We advise a thickness of 150 microns (5.850 microinch). Verify that the edges of the zone are clean.
- Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type.
   Video camera is recommended for the positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven. Below please find, the typical profile to use.
- 4. Cleaning of printed circuit boards.
- 5. Checking of solder joints and position of the component by visual inspection.

#### TEMPERATURE PROFILE



Parmeter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

Issue: 0444 C



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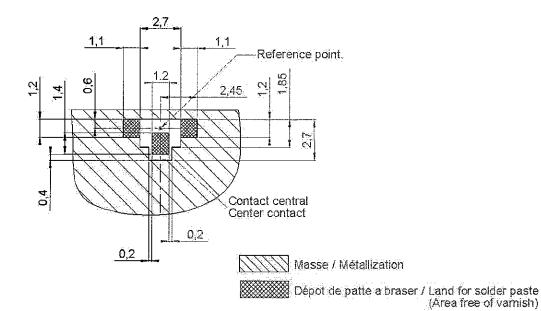
**REEL OF 100** 

Series: IMP

#### IMP SERIES INFORMATION

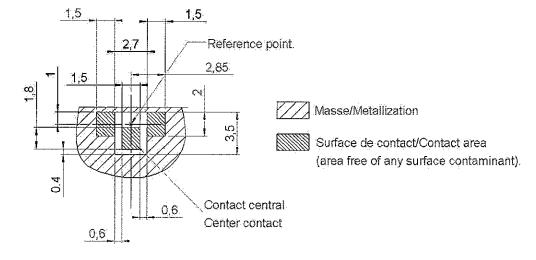
All dimension are in mm

## PCB 1



Vias and transmission line inside PCB are not represented. The impedance of the transmission line should be 50 ohms

PCB 2



Vias and transmission line inside PCB are not represented. The impedance of the transmission line should be 50 ohrns

Issue: 0444 C

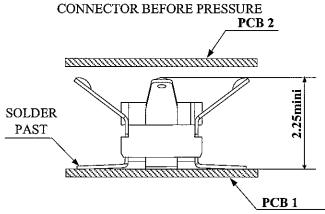


REEL OF 100

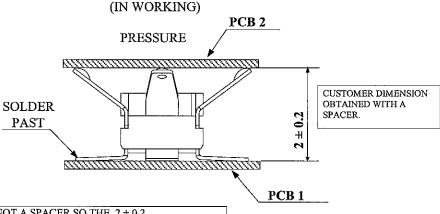
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# IMP-SERIES-INFORMATION



## CONNECTOR IN PRESSURE (IN WORKING)

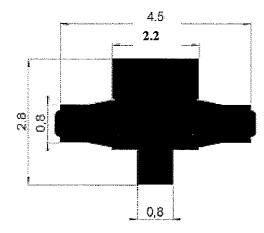


THE CONNECTOR IS NOT A SPACER, SO THE 2 ± 0.2

DIMENSION A MUST BE ENSURED WITH AN ADDED PIECE
PART SETTED 10 mm MAX.FAR FROM THE IMP CONNECTOR.

# Shadow of IMP receptacle for video camera.

All dimensions are in mm.



Issue: 0444 C

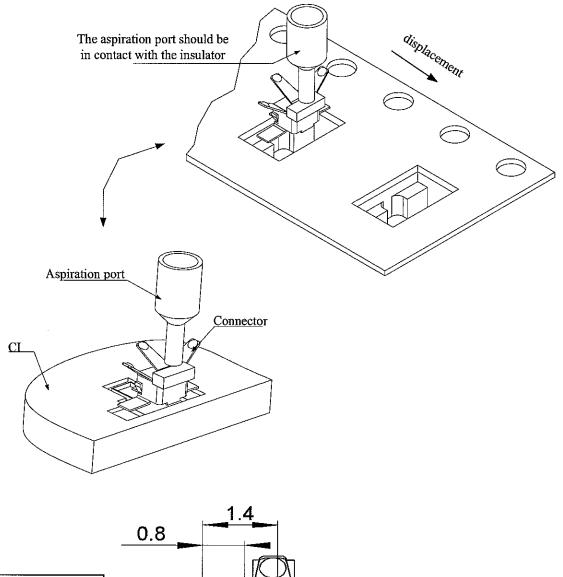


**REEL OF 100** 

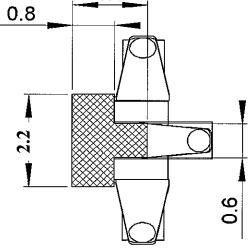
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#### **IMP-SERIES-INFORMATION**



Aspiration area



Issue: 0444 C

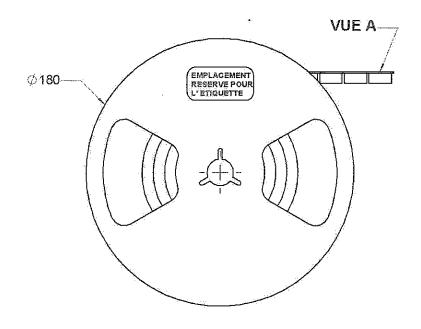


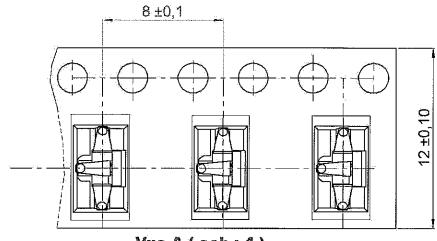
**REEL OF 100** 

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#### **IMP-SERIES-INFORMATION**





Vue A (ech: 4)

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